

1. Package summary

Terminal position code Q (quad)

Package type descriptive code X2QFN

Package type industry code X2QFN12

Package style descriptive code XQFN (extremely thin quad flatpack; no leads)

Package style suffix code U (UTLP based)
Package body material type P (plastic)

IEC package outline code - -
JEDEC package outline code - -
JEITA package outline code - - -

Mounting method type S (surface mount)

Issue date 13-1-2014

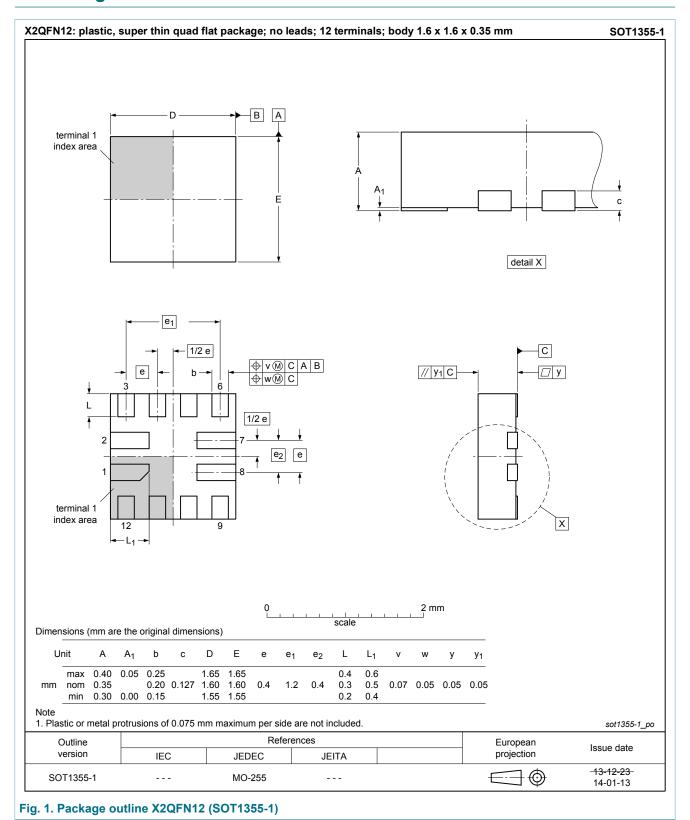
Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	1.55	-	1.6	1.65	mm
E	package width	1.55	-	1.6	1.65	mm
Α	seated height	0.3	-	0.35	0.4	mm
е	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	12	-	



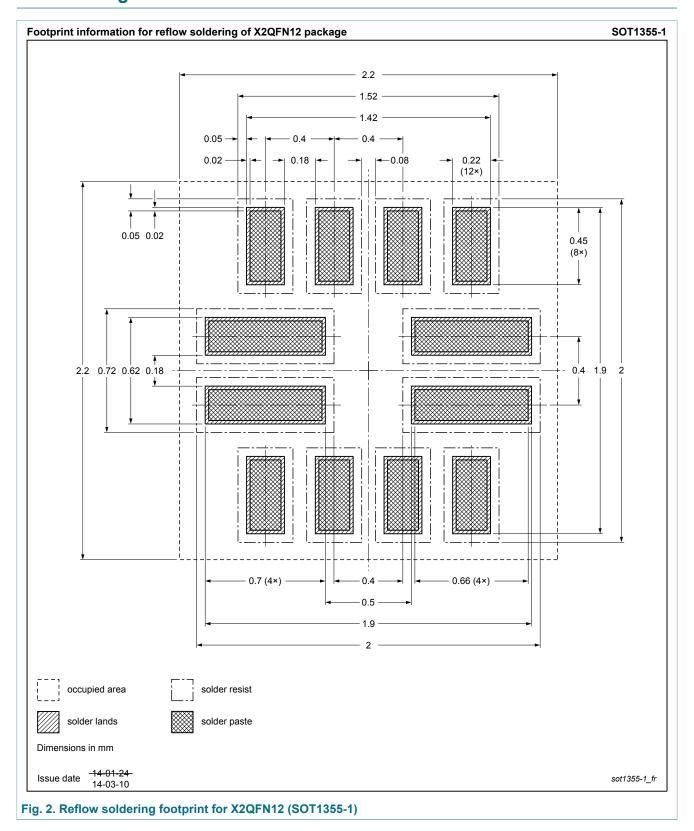
X2QFN12: plastic, super thin quad flat package; no leads; 12 terminals; body 1.6 x 1.6 x 0.35 mm

2. Package outline



X2QFN12: plastic, super thin quad flat package; no leads; 12 terminals; body 1.6 x 1.6 x 0.35 mm

3. Soldering



X2QFN12: plastic, super thin quad flat package; no leads; 12 terminals; body 1.6 x 1.6 x 0.35 mm

4. Legal information

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